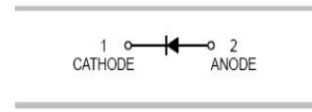


Features

- Low reverse current and low forward voltage.
- High reliability.
- Small surface mounting type.



Lead-free



SOD-323

Typical Applications

- Low current rectification.

Mechanical Data

- Case: SOD-323
- Molding compound, UL flammability classification rating 94V-0.
- Terminals: Tin plated leads, solderable per MIL-STD-202, Method 208.

Ordering Information

Part Number	Package	Shipping	Marking Code
1SS357□	SOD-323	3000/Tape Reel	S31

□: none is for Lead Free package;

“G” is for Halogen Free package.

Maximum Ratings (@T_A=25°C unless otherwise specified)

Parameter	Symbol	Value	Units
Peak Reverse Voltage	V _{RM}	45	V
DC Reverse Voltage	V _R	40	V
Average Forward Current	I _O	100	mA
Surge Current(10ms)	I _{FSM}	1	A

Thermal Characteristics

Parameter	Symbol	Value	Units
Power Dissipation	P _D	200	mW
Typical Thermal Resistance per leg	R _{θJA} *	500	°C/W
Operating Junction Temperature Range	T _J	125	°C
Storage Temperature Range	T _{STG}	-40 to +150	°C

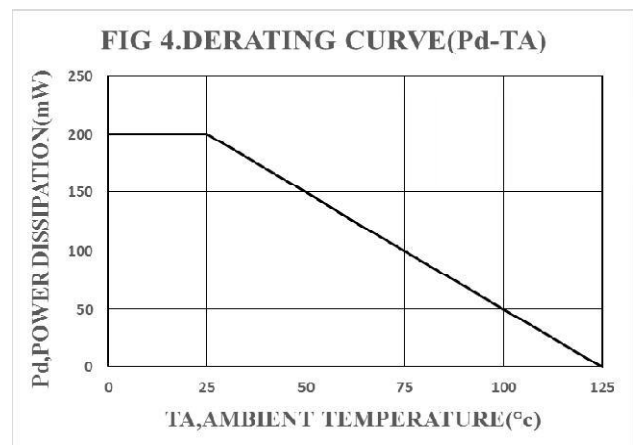
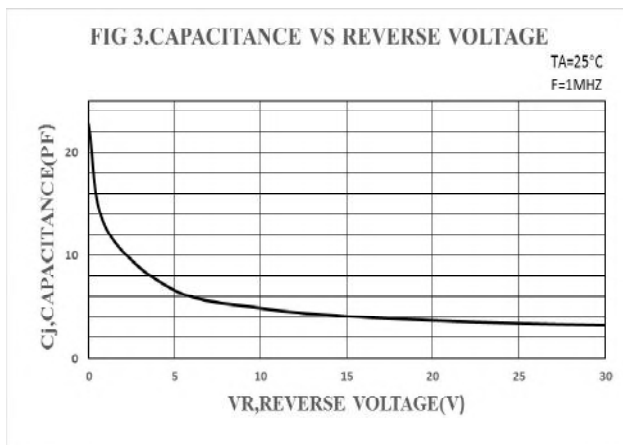
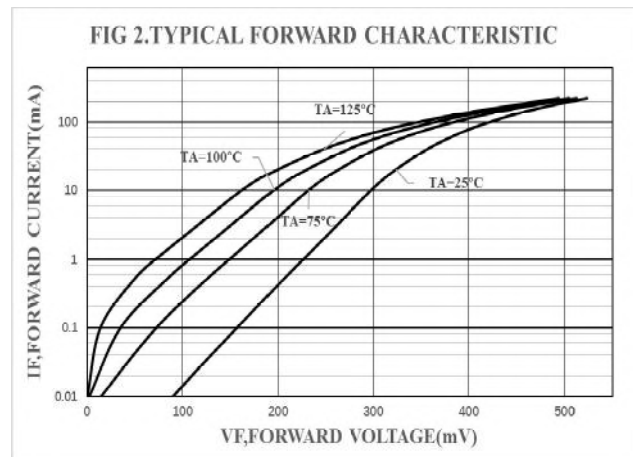
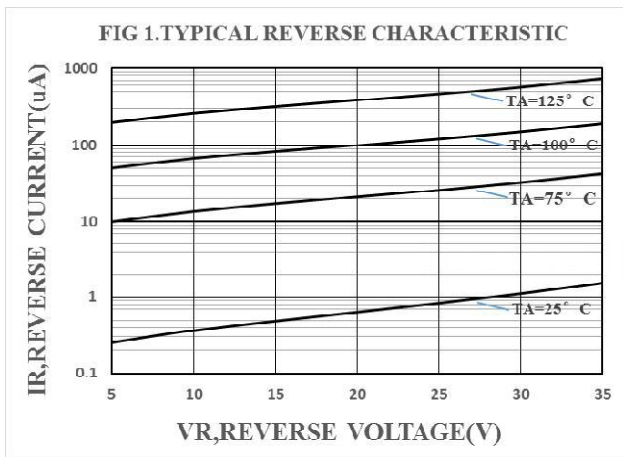
* Part mounted on FR-4 board with recommended pad layout

Electrical Characteristics (@ $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Forward Voltage	V_F^*	$I_F=1\text{mA}$	-	0.28	0.32	V
		$I_F=10\text{mA}$	-	0.36	0.38	
		$I_F=100\text{mA}$	-	0.54	0.60	
Reverse Current	I_R^{**}	$V_R=40\text{V}$	-	-	5	μA
Capacitance Between Terminals	C_T	$V_R=0\text{V}, f=1\text{MHz}$	-	18	25	pF

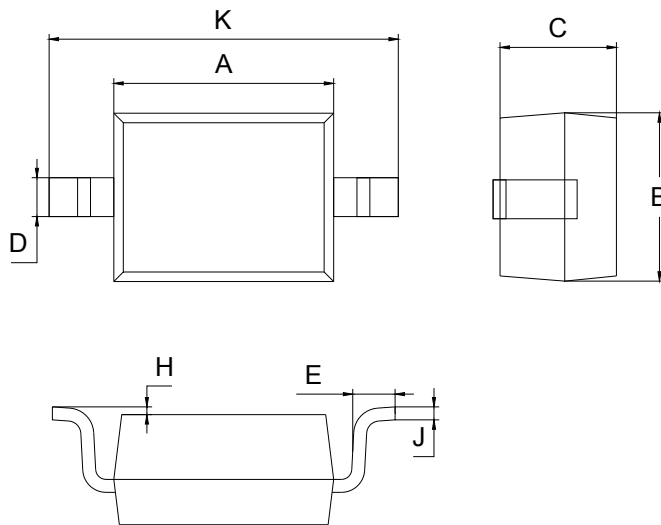
*Pulse width $\leq 380\ \mu\text{s}$, Duty cycle $< 2\%$
 **pulse test, $t_p \leq 5\text{ms}$

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)



Package Outline Dimensions (unit:mm)

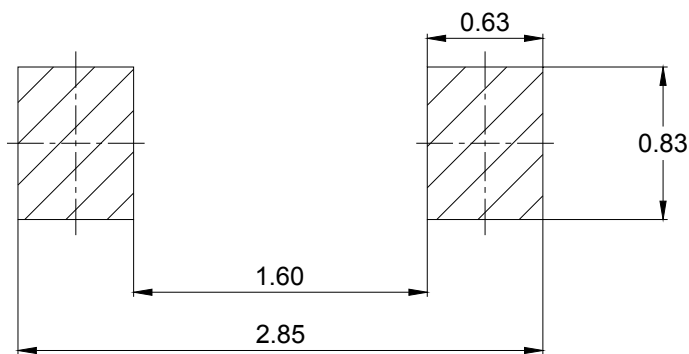
SOD-323



SOD-323		
Dim	Min	Max
A	1.60	1.80
B	1.20	1.40
C	0.80	0.90
D	0.25	0.35
E	0.22	0.42
H	0.02	0.10
J	0.05	0.15
K	2.55	2.75

Mounting Pad Layout (unit:mm)

SOD-323



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